1. General description

NPN general-purpose transistor in an ultra small DFN1110D-3 (SOT8015) leadless Surface-Mounted Device (SMD) plastic package with side-wettable flanks.

Table 1. Product overview

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>JEDEC</th>
<th>Version</th>
<th>PNP complement</th>
</tr>
</thead>
<tbody>
<tr>
<td>BC817-16QB-Q</td>
<td>DFN1110D-3</td>
<td>MO340-BA</td>
<td>SOT8015</td>
<td>BC807-16QB-Q</td>
</tr>
<tr>
<td>BC817-25QB-Q</td>
<td></td>
<td></td>
<td></td>
<td>BC807-25QB-Q</td>
</tr>
<tr>
<td>BC817-40QB-Q</td>
<td></td>
<td></td>
<td></td>
<td>BC807-40QB-Q</td>
</tr>
</tbody>
</table>

2. Features and benefits

- High power dissipation capability
- High current
- Three current gain selections
- Suitable for Automatic Optical Inspection (AOI) of solder joint
- Smaller footprint compared to conventional leaded SMD packages
- Low package height of 0.5 mm
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- General-purpose switching and amplification
- Space restricted applications

4. Quick reference data

Table 2. Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{CEO}$</td>
<td>collector-emitter voltage</td>
<td>open base; $T_{amb} = 25$ °C</td>
<td>-</td>
<td>-</td>
<td>45</td>
<td>V</td>
</tr>
<tr>
<td>$I_C$</td>
<td>collector current</td>
<td>$T_{amb} = 25$ °C</td>
<td>-</td>
<td>-</td>
<td>500</td>
<td>mA</td>
</tr>
<tr>
<td>$I_{CM}$</td>
<td>peak collector current</td>
<td>single pulse; $t_p \leq 1$ ms; $T_{amb} = 25$ °C</td>
<td>-</td>
<td>-</td>
<td>1</td>
<td>A</td>
</tr>
<tr>
<td>$h_{FE}$</td>
<td>DC current gain</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>BC817-16QB-Q</td>
<td>$V_{CE} = 1$ V; $I_C = 100$ mA $T_{amb} = 25$ °C</td>
<td>[1] 100</td>
<td>-</td>
<td>250</td>
<td></td>
<td></td>
</tr>
<tr>
<td>BC817-25QB-Q</td>
<td>$V_{CE} = 1$ V; $I_C = 100$ mA $T_{amb} = 25$ °C</td>
<td>[1] 160</td>
<td>-</td>
<td>400</td>
<td></td>
<td></td>
</tr>
<tr>
<td>BC817-40QB-Q</td>
<td>$V_{CE} = 1$ V; $I_C = 100$ mA $T_{amb} = 25$ °C</td>
<td>[1] 250</td>
<td>-</td>
<td>600</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

[1] pulsed; $t_p \leq 300$ μs; $\delta \leq 0.02$
5. Pinning information

Table 3. Pinning

<table>
<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
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<tbody>
<tr>
<td>1</td>
<td>B</td>
<td>base</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>E</td>
<td>emitter</td>
<td></td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>C</td>
<td>collector</td>
<td></td>
<td>DFN1110D-3 (SOT8015)</td>
</tr>
</tbody>
</table>

6. Ordering information

Table 4. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package Name</th>
<th>Description</th>
<th>Version</th>
</tr>
</thead>
<tbody>
<tr>
<td>BC817-16QB-Q</td>
<td>DFN1110D-3</td>
<td>DFN1110D-3: plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body: 1.1 x 1.0 x 0.5 mm</td>
<td>SOT8015 (MO340-BA)</td>
</tr>
<tr>
<td>BC817-25QB-Q</td>
<td>DFN1110D-3</td>
<td></td>
<td></td>
</tr>
<tr>
<td>BC817-40QB-Q</td>
<td>DFN1110D-3</td>
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7. Marking

Table 5. Marking

<table>
<thead>
<tr>
<th>Type number</th>
<th>Marking code</th>
</tr>
</thead>
<tbody>
<tr>
<td>BC817-16QB-Q</td>
<td>B3</td>
</tr>
<tr>
<td>BC817-25QB-Q</td>
<td>B4</td>
</tr>
<tr>
<td>BC817-40QB-Q</td>
<td>B5</td>
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</tbody>
</table>
8. Limiting values

Table 6. Limiting values

_In accordance with the Absolute Maximum Rating System (IEC 60134)._  

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>V_{CBO}</td>
<td>collector-base voltage</td>
<td>open emitter; $T_{amb} = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>50</td>
<td>V</td>
</tr>
<tr>
<td>V_{CEO}</td>
<td>collector-emitter voltage</td>
<td>open base; $T_{amb} = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>45</td>
<td>V</td>
</tr>
<tr>
<td>V_{EBO}</td>
<td>emitter-base voltage</td>
<td>open collector; $T_{amb} = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>5</td>
<td>V</td>
</tr>
<tr>
<td>I_{C}</td>
<td>collector current</td>
<td>$T_{amb} = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>500</td>
<td>mA</td>
</tr>
<tr>
<td>I_{CM}</td>
<td>peak collector current</td>
<td>single pulse; $t_p \leq 1 , \text{ms}; T_{amb} = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>1</td>
<td>A</td>
</tr>
<tr>
<td>I_{BM}</td>
<td>peak base current</td>
<td>single pulse; $t_p \leq 1 , \text{ms}; T_{amb} = 25 , ^\circ\text{C}$</td>
<td>-</td>
<td>200</td>
<td>mA</td>
</tr>
<tr>
<td>P_{tot}</td>
<td>total power dissipation</td>
<td>$T_{amb} = 25 , ^\circ\text{C}$</td>
<td>[1]</td>
<td>350</td>
<td>mW</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[2]</td>
<td>460</td>
<td>mW</td>
</tr>
<tr>
<td>T_{j}</td>
<td>junction temperature</td>
<td></td>
<td>-</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>T_{amb}</td>
<td>ambient temperature</td>
<td></td>
<td>-55</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>T_{stg}</td>
<td>storage temperature</td>
<td></td>
<td>-65</td>
<td>150</td>
<td>°C</td>
</tr>
</tbody>
</table>


(1) FR4 PCB; single-sided 70 μm copper, tin-plated and standard footprint  
(2) FR4 PCB; single-sided 35 μm copper, tin-plated and standard footprint

Fig. 1. Power derating curves for SOT8015
## 9. Thermal characteristics

### Table 7. Thermal characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$R_{th(j-a)}$</td>
<td>thermal resistance from junction to ambient</td>
<td>in free air; $T_{amb} = 25$ °C [1]</td>
<td>-</td>
<td>-</td>
<td>358</td>
<td>K/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Device mounted on an FR4 PCB, single-sided 35 μm copper, tin-plated and standard footprint. [1]</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>Device mounted on an FR4 PCB, single-sided 70 μm copper, tin-plated and standard footprint. [2]</td>
<td></td>
<td></td>
<td>272</td>
<td>K/W</td>
</tr>
</tbody>
</table>


---

**Fig. 2.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

**Fig. 3.** Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
## 10. Characteristics

### Table 8. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{(BR)CBO}$</td>
<td>collector-base breakdown voltage</td>
<td>$I_C = 100 , \mu A; , I_E = 0 , A; , T_{amb} = 25 , ^\circ C$</td>
<td>50</td>
<td>-</td>
<td>-</td>
<td>V</td>
</tr>
<tr>
<td>$V_{(BR)CEO}$</td>
<td>collector-emitter breakdown voltage</td>
<td>$I_C = 10 , mA; , I_E = 0 , A; , T_{amb} = 25 , ^\circ C$</td>
<td>45</td>
<td>-</td>
<td>-</td>
<td>V</td>
</tr>
<tr>
<td>$V_{(BR)EBO}$</td>
<td>emitter-base breakdown voltage</td>
<td>$I_E = 100 , \mu A; , I_C = 0 , A; , T_{amb} = 25 , ^\circ C$</td>
<td>5</td>
<td>-</td>
<td>-</td>
<td>V</td>
</tr>
<tr>
<td>$I_{CBO}$</td>
<td>collector-base cut-off current</td>
<td>$V_{CB} = 20 , V; , I_E = 0 , A; , T_{amb} = 25 , ^\circ C$</td>
<td>-</td>
<td>-</td>
<td>100</td>
<td>nA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{CB} = 20 , V; , I_E = 0 , A; , T_j = 150 , ^\circ C$</td>
<td>-</td>
<td>-</td>
<td>5</td>
<td>µA</td>
</tr>
<tr>
<td>$I_{EBO}$</td>
<td>emitter-base cut-off current</td>
<td>$V_{EB} = 5 , V; , I_C = 0 , A; , T_{amb} = 25 , ^\circ C$</td>
<td>-</td>
<td>-</td>
<td>100</td>
<td>nA</td>
</tr>
<tr>
<td>$h_{FE}$</td>
<td>DC current gain</td>
<td>$V_{CE} = 1 , V; , I_C = 100 , mA; , T_{amb} = 25 , ^\circ C$</td>
<td>[1]</td>
<td>100</td>
<td>-</td>
<td>250</td>
</tr>
<tr>
<td></td>
<td></td>
<td>$V_{CE} = 1 , V; , I_C = 500 , mA; , T_{amb} = 25 , ^\circ C$</td>
<td></td>
<td>-</td>
<td>-</td>
<td></td>
</tr>
<tr>
<td>$V_{CEsat}$</td>
<td>collector-emitter saturation voltage</td>
<td>$I_C = 500 , mA; , I_B = 50 , mA; , T_{amb} = 25 , ^\circ C$</td>
<td>[1]</td>
<td>-</td>
<td>-</td>
<td>700</td>
</tr>
<tr>
<td>$V_{BE}$</td>
<td>base-emitter voltage</td>
<td>$V_{CE} = 1 , V; , I_C = 500 , mA; , T_{amb} = 25 , ^\circ C$</td>
<td>[1]</td>
<td>-</td>
<td>-</td>
<td>1.2</td>
</tr>
<tr>
<td>$f_T$</td>
<td>transition frequency</td>
<td>$V_{CE} = 5 , V; , I_C = 10 , mA; , f = 100 , MHz; , T_{amb} = 25 , ^\circ C$</td>
<td></td>
<td>100</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td>$C_C$</td>
<td>collector capacitance</td>
<td>$V_{CB} = 10 , V; , I_E = I_a = 0 , A; , f = 1 , MHz; , T_{amb} = 25 , ^\circ C$</td>
<td></td>
<td>3</td>
<td>-</td>
<td>pF</td>
</tr>
</tbody>
</table>

[1] pulsed: $t_p \leq 300 \, \mu s; \, \delta \leq 0.02$
**Nexperia**

**BC817QB-Q series**

45 V, 500 mA NPN general-purpose transistors

---

**Fig. 4.** BC817-16QB: DC current gain as a function of collector current; typical values

\[
\begin{align*}
V_{CE} &= 1 \, \text{V} \\
(1) \ T_{amb} &= 150 \, ^\circ\text{C} \\
(2) \ T_{amb} &= 25 \, ^\circ\text{C} \\
(3) \ T_{amb} &= -55 \, ^\circ\text{C}
\end{align*}
\]

---

**Fig. 5.** BC817-16QB: Collector current as a function of collector-emitter voltage; typical values

\[
\begin{align*}
T_{amb} &= 25 \, ^\circ\text{C} \\
(1) \ I_B &= 16.0 \, \text{mA} \\
(2) \ I_B &= 14.4 \, \text{mA} \\
(3) \ I_B &= 12.8 \, \text{mA} \\
(4) \ I_B &= 11.2 \, \text{mA} \\
(5) \ I_B &= 9.6 \, \text{mA} \\
(6) \ I_B &= 8.0 \, \text{mA} \\
(7) \ I_B &= 6.4 \, \text{mA} \\
(8) \ I_B &= 4.8 \, \text{mA} \\
(9) \ I_B &= 3.2 \, \text{mA} \\
(10) \ I_B &= 1.6 \, \text{mA}
\end{align*}
\]

---

**Fig. 6.** BC817-16QB: Base-emitter saturation voltage as a function of collector current; typical values

\[
\begin{align*}
\frac{I_C}{I_B} &= 10 \\
(1) \ T_{amb} &= -55 \, ^\circ\text{C} \\
(2) \ T_{amb} &= 25 \, ^\circ\text{C} \\
(3) \ T_{amb} &= 150 \, ^\circ\text{C}
\end{align*}
\]

---

**Fig. 7.** BC817-16QB: Collector-emitter saturation voltage as a function of collector current; typical values

\[
\begin{align*}
\frac{I_C}{I_B} &= 10 \\
(1) \ T_{amb} &= 150 \, ^\circ\text{C} \\
(2) \ T_{amb} &= 25 \, ^\circ\text{C} \\
(3) \ T_{amb} &= -55 \, ^\circ\text{C}
\end{align*}
\]
**BC817QB-Q series**

45 V, 500 mA NPN general-purpose transistors

---

**Fig. 8. BC817-25QB: DC current gain as a function of collector current; typical values**

*V_{CE} = 1 V*

1. \( T_{\text{amb}} = 150 \, ^\circ\text{C} \)
2. \( T_{\text{amb}} = 25 \, ^\circ\text{C} \)
3. \( T_{\text{amb}} = -55 \, ^\circ\text{C} \)

**Fig. 9. BC817-25QB: Collector current as a function of collector-emitter voltage; typical values**

*\( T_{\text{amb}} = 25 \, ^\circ\text{C} \)*

1. \( I_{B} = 13.0 \, \text{mA} \)
2. \( I_{B} = 11.7 \, \text{mA} \)
3. \( I_{B} = 10.4 \, \text{mA} \)
4. \( I_{B} = 9.1 \, \text{mA} \)
5. \( I_{B} = 7.8 \, \text{mA} \)
6. \( I_{B} = 6.5 \, \text{mA} \)
7. \( I_{B} = 5.2 \, \text{mA} \)
8. \( I_{B} = 3.9 \, \text{mA} \)
9. \( I_{B} = 2.6 \, \text{mA} \)
10. \( I_{B} = 1.3 \, \text{mA} \)

**Fig. 10. BC817-25QB: Base-emitter saturation voltage as a function of collector current; typical values**

*IC/IB = 10*

1. \( T_{\text{amb}} = -55 \, ^\circ\text{C} \)
2. \( T_{\text{amb}} = 25 \, ^\circ\text{C} \)
3. \( T_{\text{amb}} = 150 \, ^\circ\text{C} \)

**Fig. 11. BC817-25QB: Collector-emitter saturation voltage as a function of collector current; typical values**

*IC/IB = 10*

1. \( T_{\text{amb}} = 150 \, ^\circ\text{C} \)
2. \( T_{\text{amb}} = 25 \, ^\circ\text{C} \)
3. \( T_{\text{amb}} = -55 \, ^\circ\text{C} \)
**BC817QB-Q series**

45 V, 500 mA NPN general-purpose transistors

---

**Fig. 12.** BC817-40QB-Q: DC current gain as a function of collector current; typical values

- $V_{CE} = 1$ V
- (1) $T_{amb} = 150 \degree C$
- (2) $T_{amb} = 25 \degree C$
- (3) $T_{amb} = -55 \degree C$

---

**Fig. 13.** BC817-40QB : Transition frequency as a function of collector current; typical values

- $I_{B} = 12.0$ mA
- (1) $T_{amb} = -55 \degree C$
- (2) $T_{amb} = 25 \degree C$
- (3) $T_{amb} = 150 \degree C$
- (4) $I_{B} = 8.4$ mA
- (5) $I_{B} = 7.2$ mA
- (6) $I_{B} = 6.0$ mA
- (7) $I_{B} = 4.8$ mA
- (8) $I_{B} = 3.6$ mA
- (9) $I_{B} = 2.4$ mA
- (10) $I_{B} = 1.2$ mA

---

**Fig. 14.** BC817-40QB-Q: Base-emitter saturation voltage as a function of collector current; typical values

- $I_{C}/I_{B} = 10$
- (1) $T_{amb} = -55 \degree C$
- (2) $T_{amb} = 25 \degree C$
- (3) $T_{amb} = 150 \degree C$

---

**Fig. 15.** BC817-40QB-Q: Collector-emitter saturation voltage as a function of collector current; typical values

- $I_{C}/I_{B} = 10$
- (1) $T_{amb} = 150 \degree C$
- (2) $T_{amb} = 25 \degree C$
- (3) $T_{amb} = -55 \degree C$
11. Test information

11.1. Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.
12. Package outline

DFN1110D-3: plastic, leadless extremely thin small outline package with side-wettable flanks (SWF);
3 terminals; 0.65 mm pitch; 1.1 mm x 1 mm x 0.48 mm body

Dimensions (mm are the original dimensions)

<table>
<thead>
<tr>
<th>Unit</th>
<th>A</th>
<th>A1</th>
<th>b</th>
<th>D</th>
<th>D1</th>
<th>E1</th>
<th>E</th>
<th>e1</th>
<th>e2</th>
<th>G</th>
<th>K</th>
<th>L</th>
<th>T</th>
<th>u</th>
<th>v</th>
<th>w</th>
<th>y</th>
<th>y1</th>
</tr>
</thead>
<tbody>
<tr>
<td>mm</td>
<td>0.50</td>
<td>0.040</td>
<td>0.30</td>
<td>0.95</td>
<td>0.48</td>
<td>0.43</td>
<td>0.65</td>
<td>0.58</td>
<td>0.19</td>
<td>0.09</td>
<td>0.005</td>
<td>0.20</td>
<td>0.23</td>
<td>0.16</td>
<td>0.05</td>
<td>0.1</td>
<td>0.05</td>
<td>0.05</td>
</tr>
<tr>
<td>nom</td>
<td>0.47</td>
<td>0.020</td>
<td>0.25</td>
<td>1.1</td>
<td>0.90</td>
<td>1</td>
<td>0.43</td>
<td>0.65</td>
<td>0.58</td>
<td>0.19</td>
<td>0.09</td>
<td>0.005</td>
<td>0.20</td>
<td>0.23</td>
<td>0.16</td>
<td>0.05</td>
<td>0.1</td>
<td>0.05</td>
</tr>
<tr>
<td>min</td>
<td>0.44</td>
<td>0.005</td>
<td>0.22</td>
<td>0.87</td>
<td>0.40</td>
<td></td>
<td></td>
<td></td>
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<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Note:
1. Side Wettable Flank, protrusion max. 0.02 mm.
2. Visible depend upon used manufacturing technology.
3. Included plating thickness.

Fig. 16. Package outline DFN1110D-3 (SOT8015)
13. Soldering

Fig. 17. Reflow soldering footprint for DFN1110D-3 (SOT8015)
## 14. Revision history

<table>
<thead>
<tr>
<th>Document ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
</tr>
</thead>
<tbody>
<tr>
<td>BC817QB-Q_SER v.2</td>
<td>20210504</td>
<td>Product data sheet</td>
<td>-</td>
<td>BC817QB-Q_SER v.1</td>
</tr>
<tr>
<td>Modifications:</td>
<td></td>
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<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td>Features and benefits: added recommendation for automotive applications</td>
</tr>
<tr>
<td>BC817QB-Q_SER v.1</td>
<td>20210219</td>
<td>Product data sheet</td>
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15. Legal information

Data sheet status

<table>
<thead>
<tr>
<th>Document status</th>
<th>Product status</th>
<th>Definition</th>
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<tbody>
<tr>
<td>[1][2]</td>
<td>[3]</td>
<td>This document contains data from the objective specification for product development.</td>
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<tr>
<td>Objective [short] data sheet</td>
<td>Development</td>
<td>This document contains data from the preliminary specification.</td>
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<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
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<tr>
<td>Product [short] data sheet</td>
<td>Production</td>
<td>This document contains the product specification.</td>
</tr>
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</table>

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term "short data sheet" is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published. For the latest product status information, please see the product's web page on the internet at https://www.nexperia.com.

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